

Features

- DC - 2.5 GHz
- 8 Watts
- BeO Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

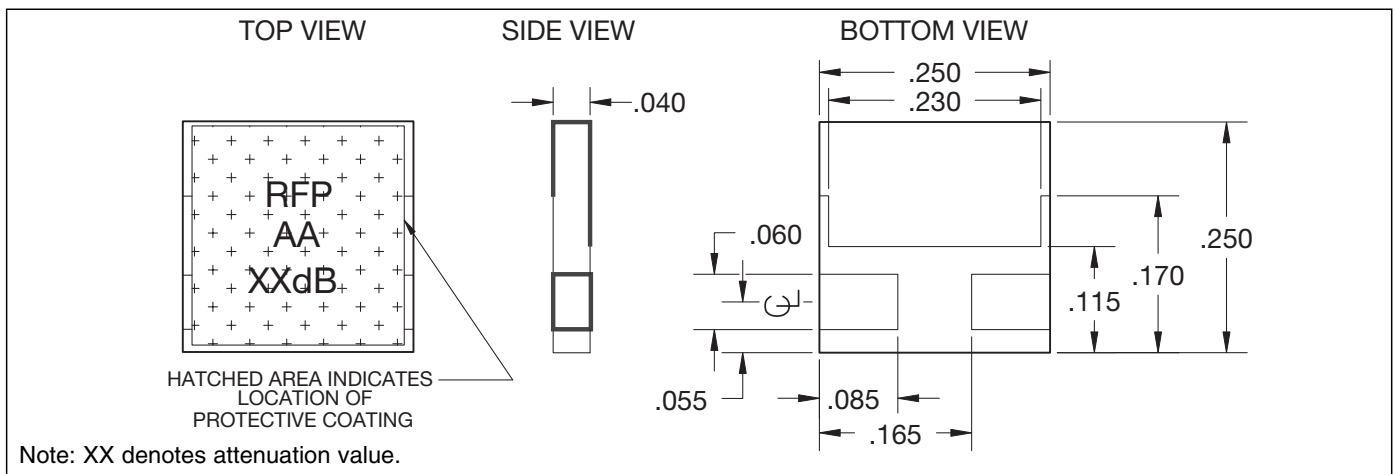
Resistive Element:	Thick film
Substrate:	Beryllium oxide ceramic
Terminals:	Thick film silver

Electrical Specifications

Attenuation Value:	1, 2, 3, 4, 5, 6, 9, 10, 20 or 30 dB
Frequency Range:	DC - 2.5 GHz
Power:	8 Watts

Notes: Tolerance is ± 0.10 , unless otherwise specified. Operating temperature is -55°C to $+150^{\circ}\text{C}$ (see chart). Designed to meet or exceed applicable portions of MIL-E-5400. All dimensions are in inches. **Specifications subject to change without notice.**

Outline Drawing



VER. 12/5/01



Available on Tape and Reel for Pick and Place Manufacturing.

Sales Desk USA: Voice: (800) 544-2414 Fax: (315) 432-9121
Sales Desk Europe: Voice: (+44) 23 92 232392 Fax: (+44) 23 92 251369

Model RFP-250250-4AAXX

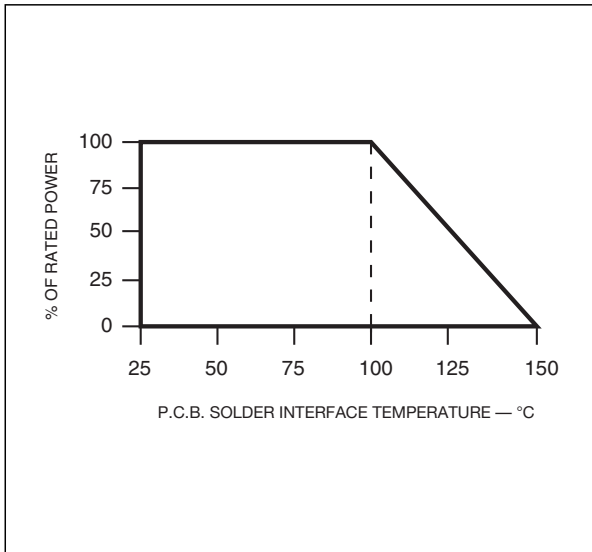


RF Power

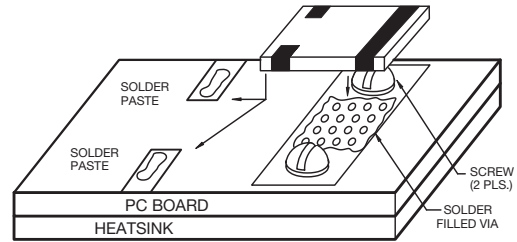
Specifications

PART NUMBER	ATTENUATION (dB)	TOL. (+/-dB)	WIDTH	LENGTH	THK	POWER (WATTS)	VSWR	FREQ.(GHz)
RFP-250250-4AA1	1	0.30	0.25	0.25	0.04	8	1.20:1	2.5
RFP-250250-4AA2	2	0.40	0.25	0.25	0.04	8	1.20:1	2.5
RFP-250250-4AA3	3	0.40	0.25	0.25	0.04	8	1.20:1	2.5
RFP-250250-4AA4	4	0.40	0.25	0.25	0.04	8	1.20:1	2.5
RFP-250250-4AA5	5	0.40	0.25	0.25	0.04	8	1.25:1	2.5
RFP-250250-4AA6	6	0.40	0.25	0.25	0.04	8	1.30:1	2.5
RFP-250250-4AA9	9	0.40	0.25	0.25	0.04	8	1.30:1	2.5
RFP-250250-4AA10	10	0.40	0.25	0.25	0.04	8	1.30:1	2.5
RFP-250250-4AA20	20	0.75	0.25	0.25	0.04	8	1.25:1	2.5
RFP-250250-4AA30	30	1.50	0.25	0.25	0.04	8	1.20:1	2.0

Power Derating



Suggested Mounting Procedures



1. Solder part in place using 60/40 type solder with controlled temperature iron (700°F).
2. Drill thermal vias through PCB and fill with solder, such as 60/40 type.
3. To ensure good thermal connectivity to heat sink, drill and tap heatsink and mount PCB board to heat sink using screws.

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